

ASNA PERFREZ® XL11

Excel chemical resistance and purity for semiconductor applications

Technical Data Sheet (Jan 2019)

Enhanced plasma resistance and physical strength

PERFREZ® XL11 offers superior plasma resistance especially aggressive fluorine based process. It also features the excellent physical properties with low CTE that mitigate any risk of extrusion due to thermal expansion.



Features and Benefits

- Excellent oxygen and fluorine compatibilities
- Excellent plasma resistance
- Superior physical properties and low CTE
- Low out-gassing
- Ultra-low particle generation

Compatible Semiconductor Process

- ✓ Deposition: CVD, APCVD, HDPCVD, RPCVD, SACVD
- ✓ Plasma Etch: oxide and metal
- ✓ Ashing
- ✓ Ion Implant
- ✓ Etch

Applications:

- ✓ Bell Jar Seals
- ✓ Chamber Lid Seals
- ✓ Door Seals
- ✓ End Point Windows
- ✓ Gas Inlet Seals
- ✓ Isolator Valve Seals
- ✓ Slit Valves
- ✓ Window Seals

Typical Physical Properties¹

Color ²	Light Beige
Hardness, (Shore A)	85 (+/-5)
Elongation at break ³ , %	142
Tensile Strength, psi(MPa)	2425(16.72)
Modulus @100%, psi(MPa)	1708(11.78)
Coefficient of Thermal Expansion	2.27x10 ⁻⁴
Min. Operating Temperature, °C(°F)	-20(-4)
Max. Operating Temperature, °C(°F)	260(500)

¹Not to be used for specification purposes

²Color variations may be observed in actual product. They are considered to be cosmetic and inherent as a result of curing process, not indicative for foreign matter and is not expected to have an adverse effect on the performance of the part in service.

³Even though elongation property is indicated, most perfluoroelastomer materials should not be stretched for optimal performance.

⁴ASTM D395-03, Method B

Applied Seals NA, Inc.

39899 Balentine Dr, Suite 368, Newark, CA 94560, USA

Toll Free: (888)551-ASNA (2762) | Direct: (510)623-8307 | Fax: (510)623-8723

Email: info@asnaglobal.com

www.asnaglobal.com



CASE STUDY: Excellent Chemical/Plasma Resistance and low CTE

Competitive FFKM (Before and after) **PERFREZ® XL11 (Before and after)**



After use: Competitor K5 material shows a high degree of discoloration.



- Competitive FFKM exhibits pitting due to blistering from the chemical attack on the surface.
- PERFREZ® XL11 shows minor chemical degradation on the surface.
- Poor design and high CTE value lead to severe extrusion.

Properties	PERFREZ® XL11	Competitive FFKM
Hardness(Shore A)	85	76
100% Modulus, MPa	11.78	9.6
Tensile Strength, MPa	16.72	16.4
Elongation, %	142	193
CTE, $\mu\text{m}/\text{m}\cdot^{\circ}\text{C}$	227	421
Vol. \uparrow in 200°C (Est.)	12%	24%

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